



IEEE SW Test Workshop
Semiconductor Wafer Test Workshop

June 12 to 15, 2011
San Diego, CA

**An Advanced Cantilever
Probe Card with 6GHz
Bandwidth for RFIC Wafer
Testing**



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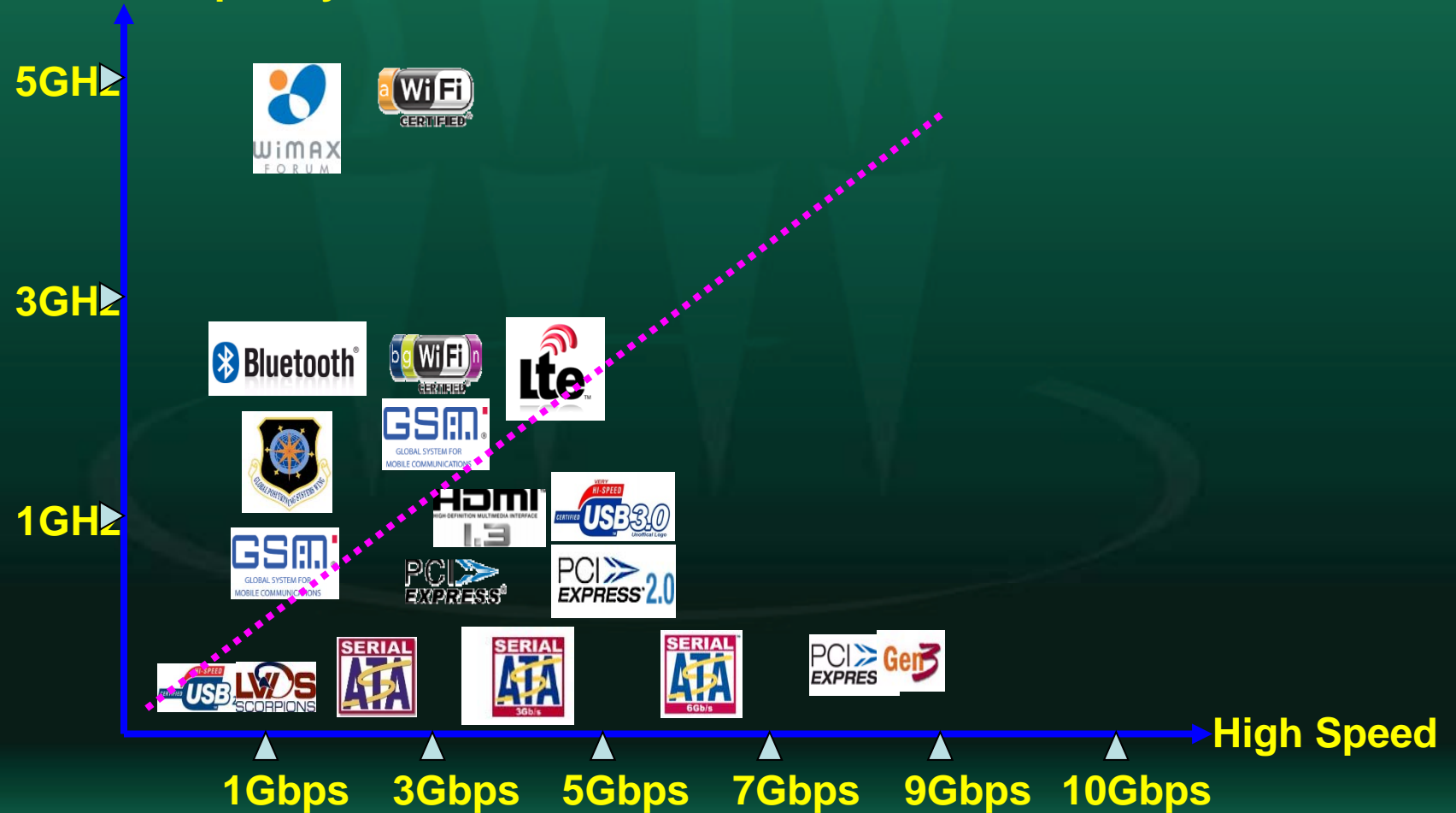
Overview

- **Background**
- **RF Cantilever Probe Card Solution**
- **RF Simulation and Modeling**
- **Experiment, Validation & Customer Verification**
- **Summary**



Background

Radio Frequency



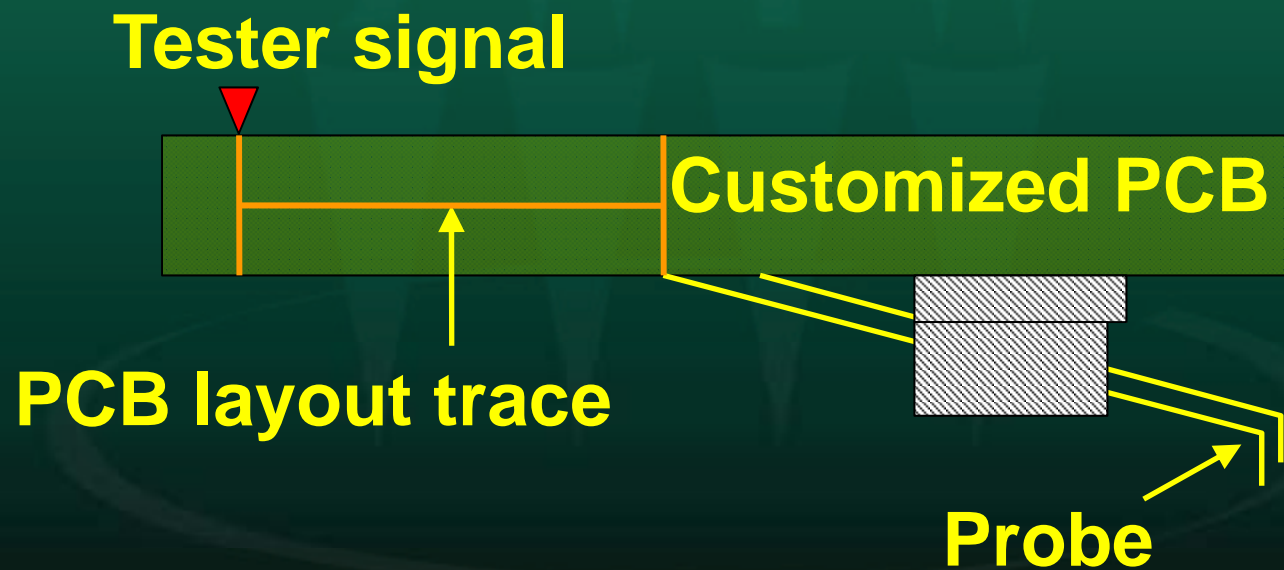
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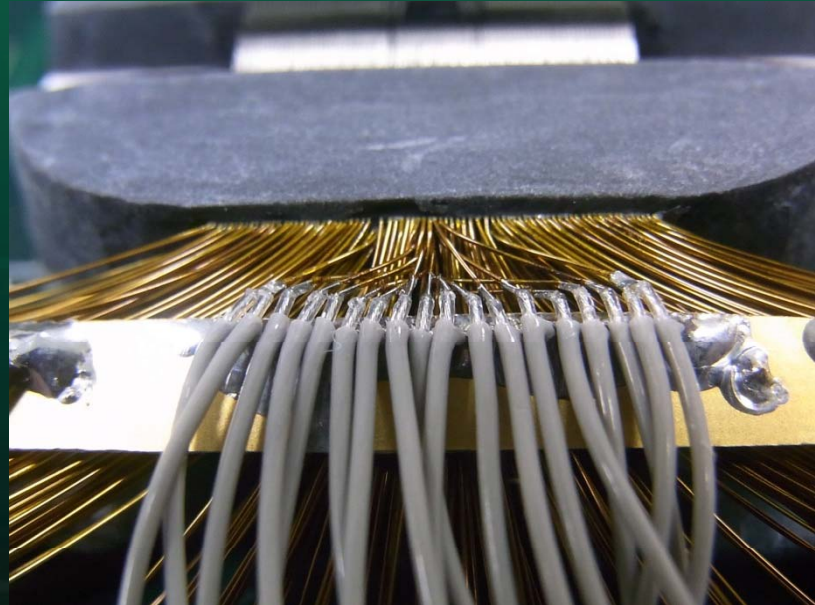
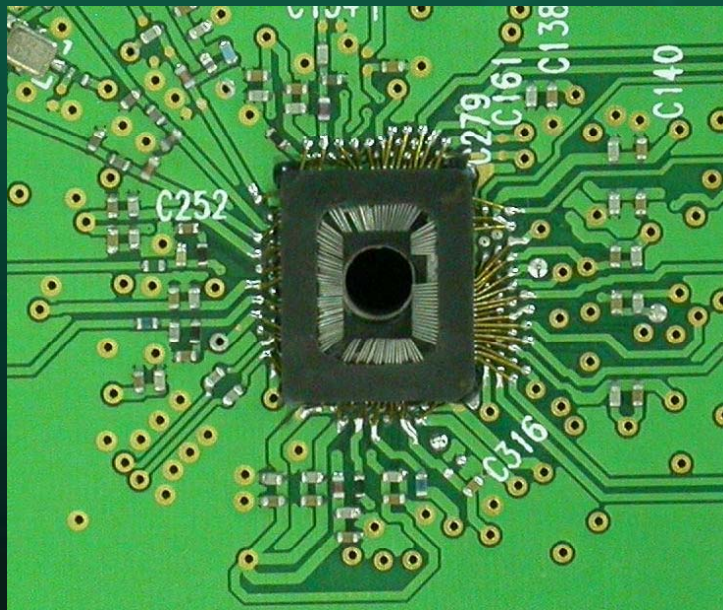
Background

- Cantilever probe card structure



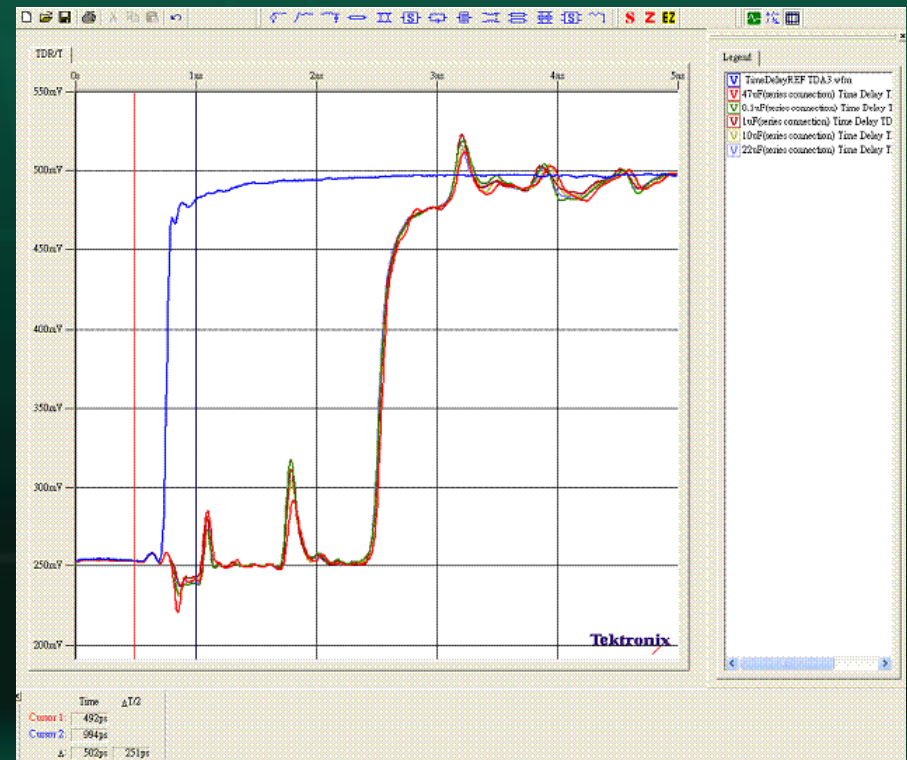
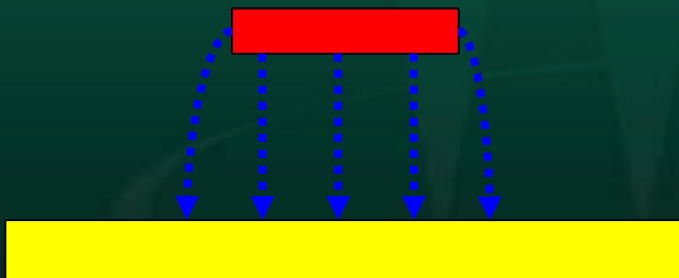
RF/HF Solution

- Traditional RF Solution

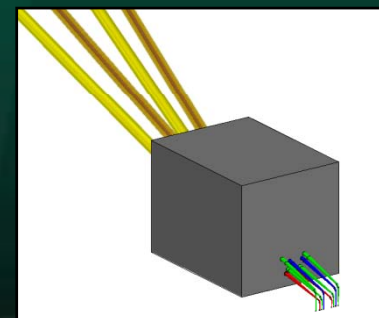
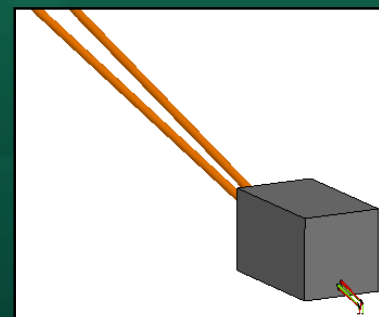
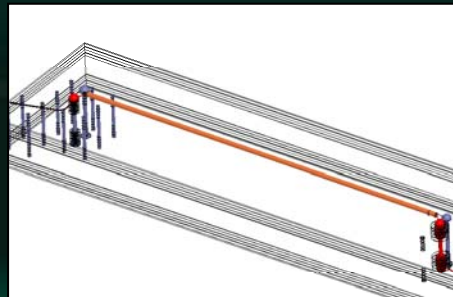
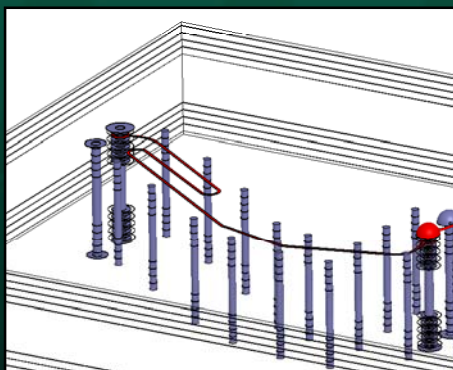
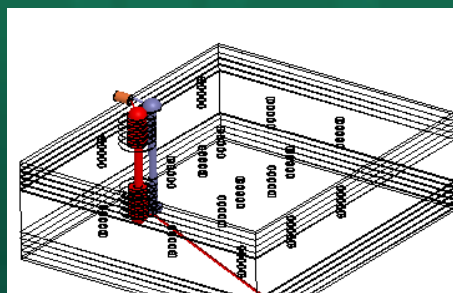
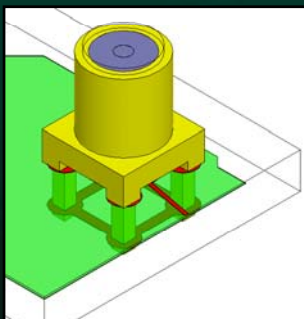
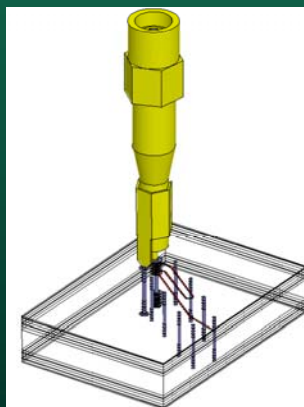


RF/HF Solution

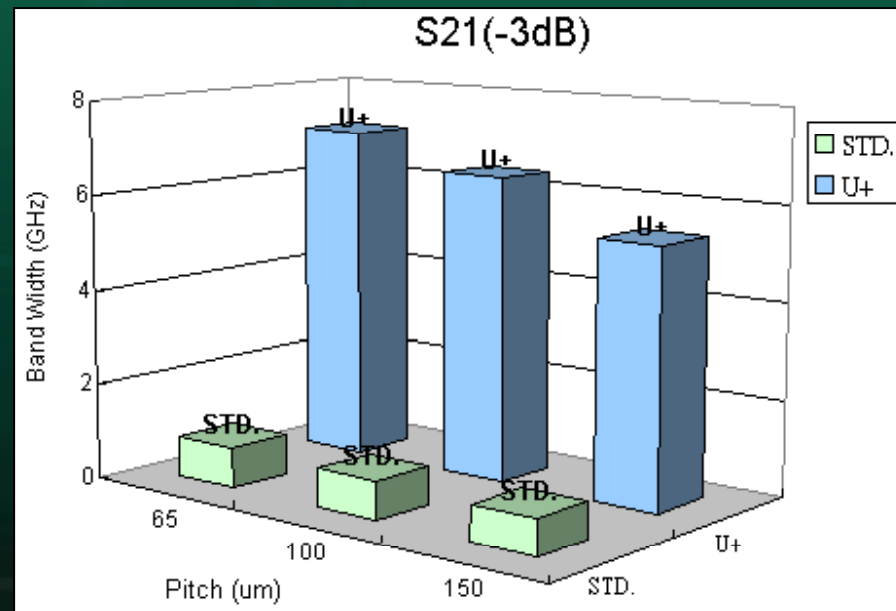
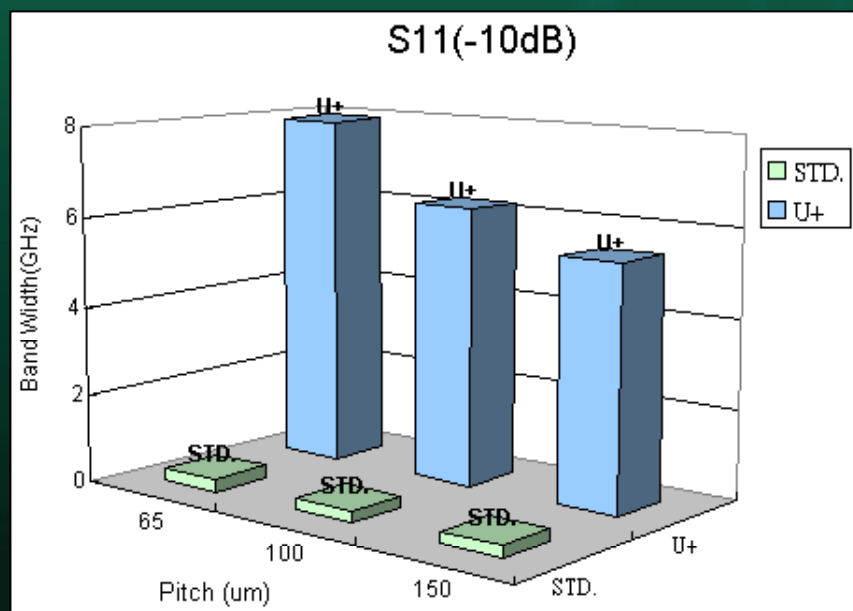
- Transmission Line Theorem
- Impedance Control



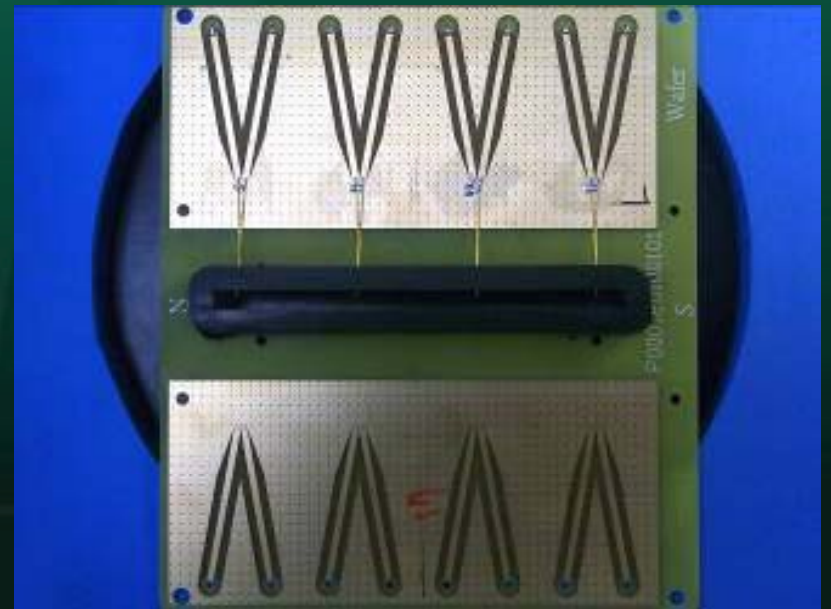
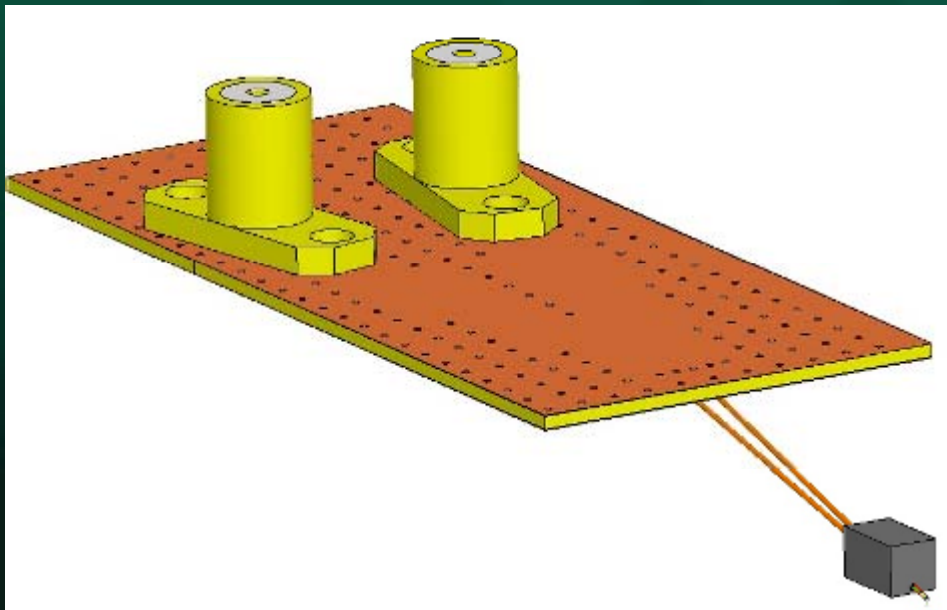
RF Simulation and Modeling



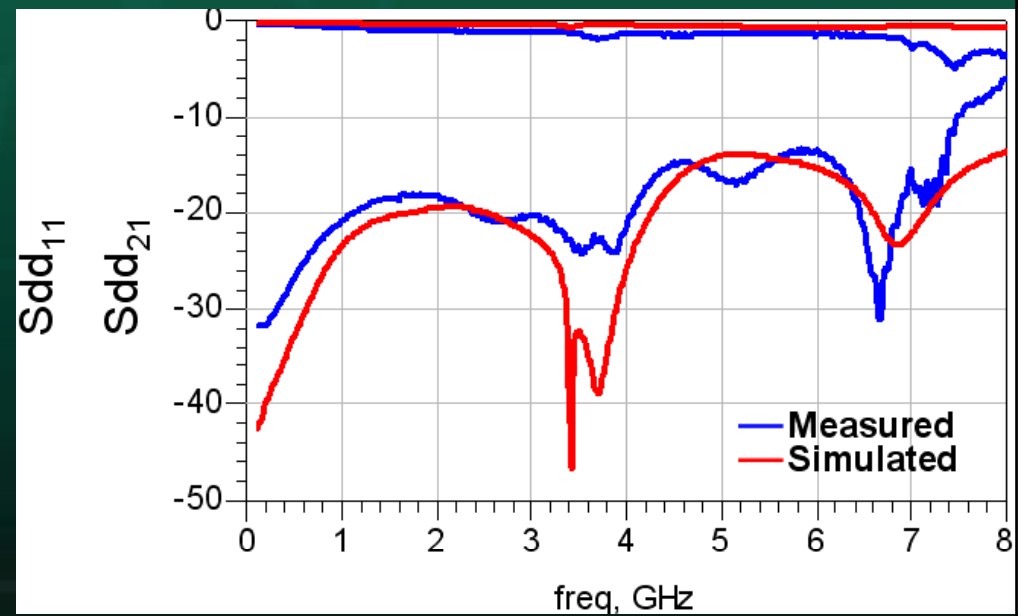
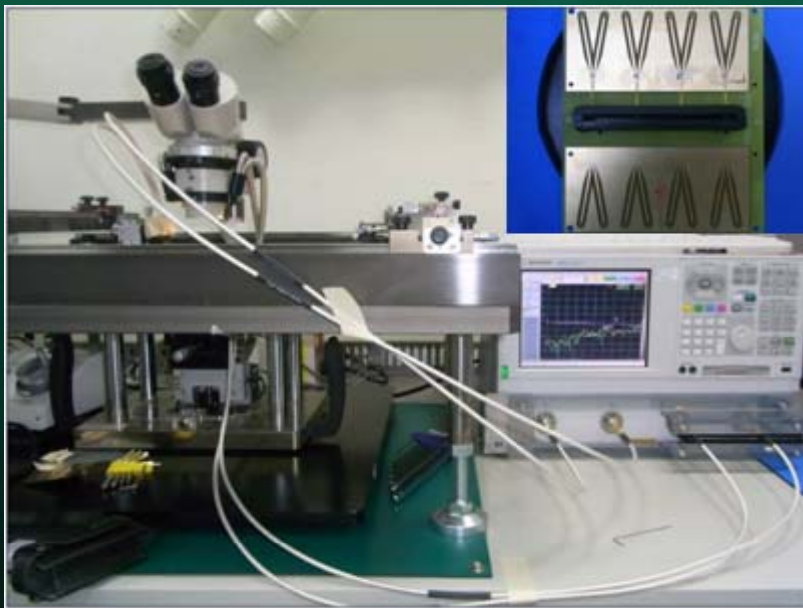
RF Simulation and Modeling



Experiment

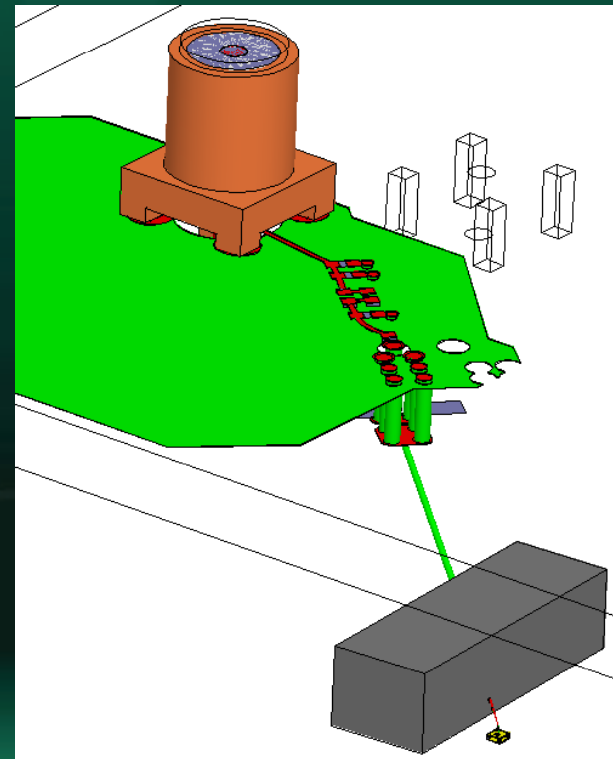
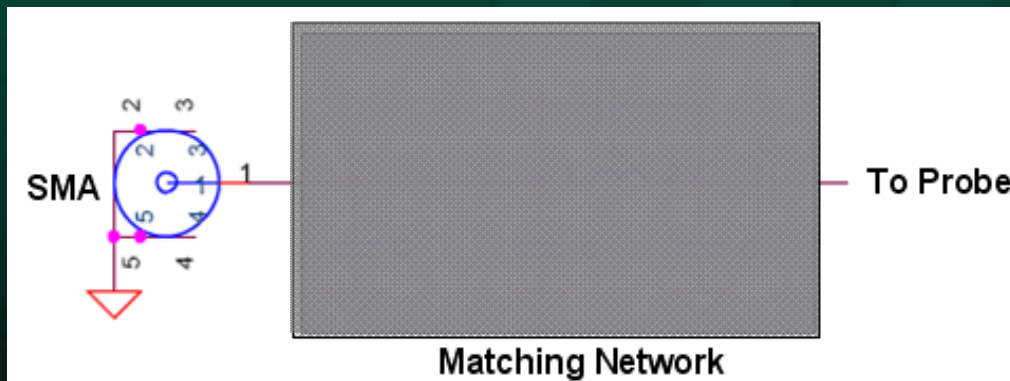


Experiment

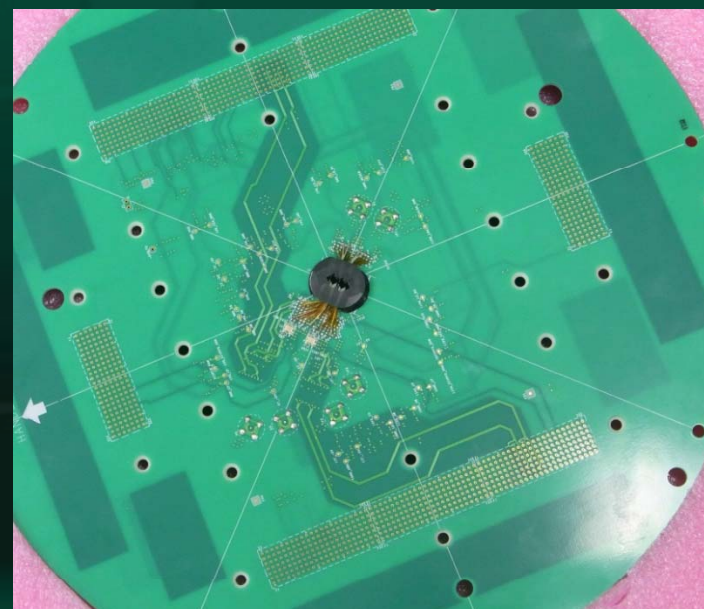
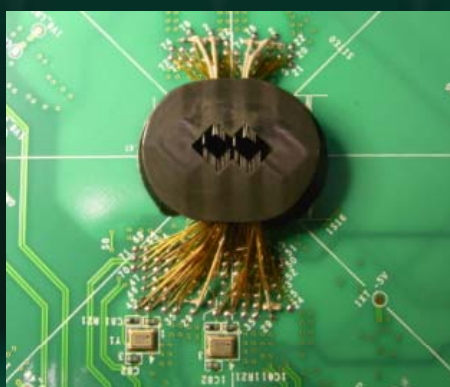


Customer Verification

- Application: RFIC
- Frequency : RF Out 2.3-3.8GHz



Customer Verification



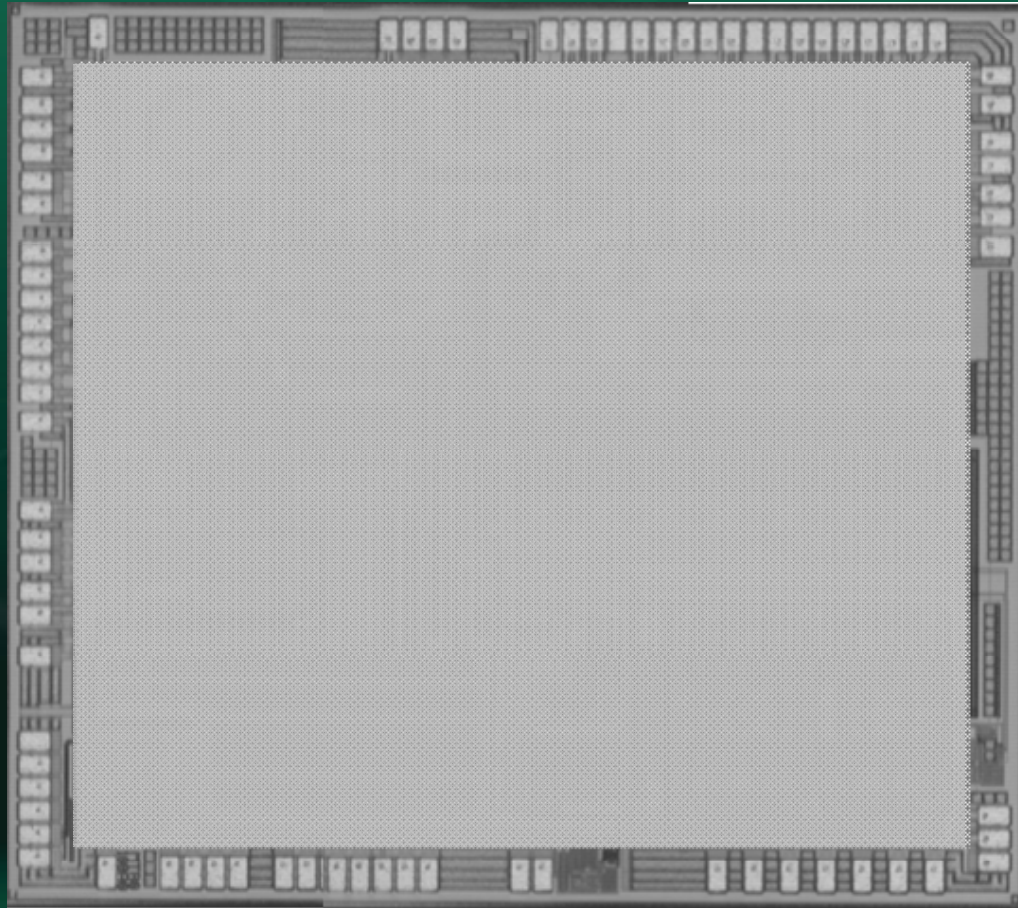
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Customer Verification

- DUT information – Probe Mark

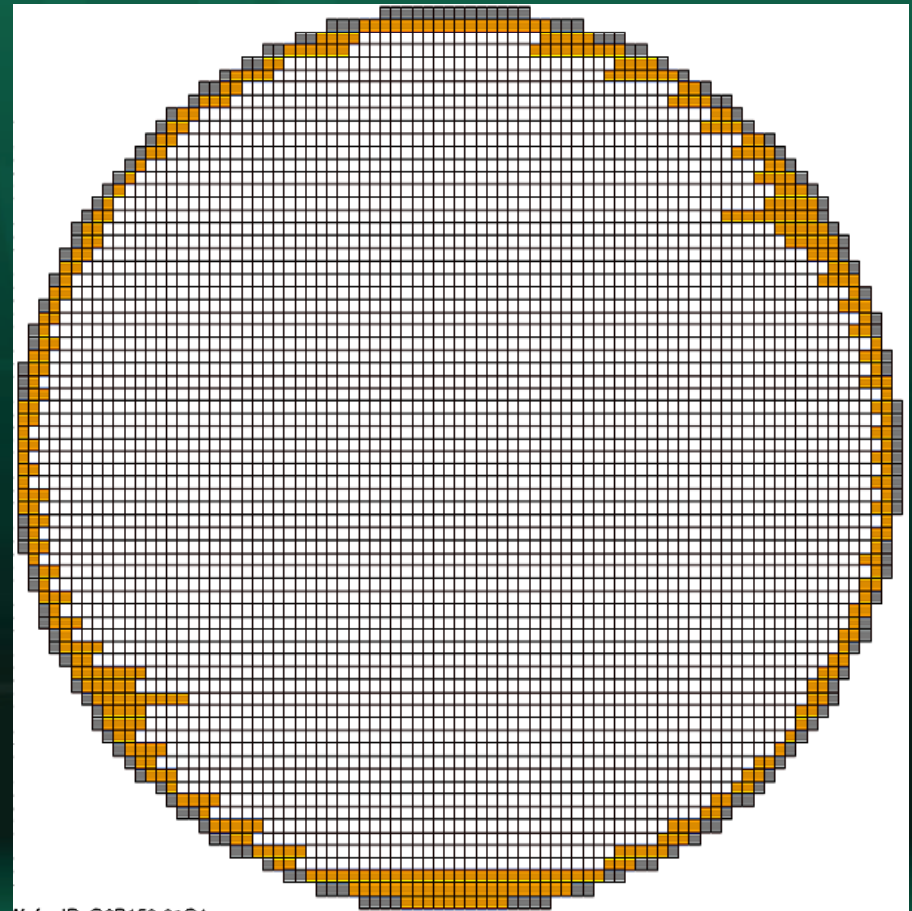


Customer Verification

- DUT information – Wafer Map**

Electrogas SECS Wafer Map Summary

Date/Time Printed: 2011-05-20 16:56:19
Date/Time Probed: 2011-05-06 16:57:53
Wafer ID: G6B150-01C4
Flat Location: 0
X Die Size= 2400, Y Die Size= 2800
Die Size Units: 10⁻⁶m
Coordinate Quadrant= 2
Reference Die X,Y= 31,3
X Coordinates: Minimum= 1, Maximum= 83
Y Coordinates: Minimum= 1, Maximum= 71
Total Die in Map: 4659

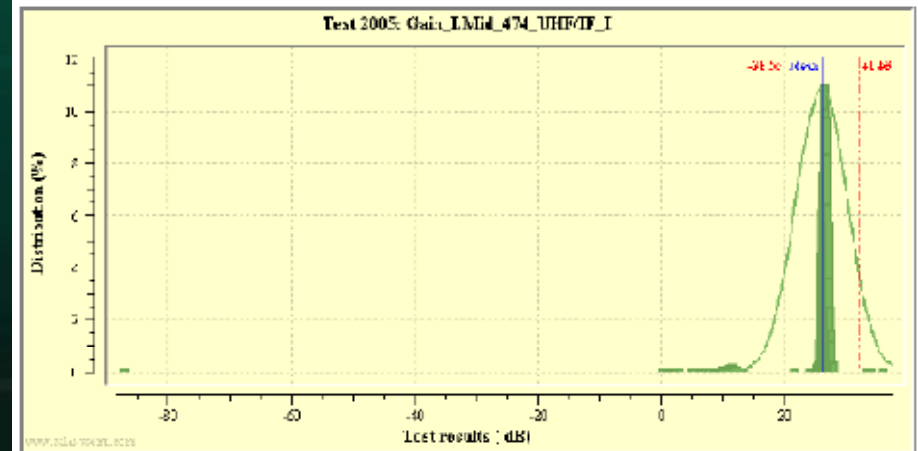


Customer Verification

- DUT information – Test Data**

Test	Name	Cp
2704	Post_I_7_634_UHFVF_I	1.35
2704	Post_Peak_634_UHFVF_I	1.39
1028	III_INFO_PWM/INPO_PWM	1.40
1023	III_DATA_THRU/DATA_OUT	1.47
2706	Post_3.8_634_UHFVF_I	1.46
2702	Preq_Peak_634_UHFVF_I	1.47
2959	P656_LPN_UHFVF_I	1.53
2941	P680_LPN_UHFVF_I	1.60
2005	Gain_LMG1_474_UHFVF_I	1.61

Test	2005
Name	Gain_LMG1_474_UHFVF_I
Test type	Parametric
Low L	20.7 dB
High L	60.0 dB
Mean / Min / Max	25.9286 dB / -86.5897 dB / 38.1069 dB (sum summary)
Mean / Min / Max	24.9786 dB / -86.5897 dB / 38.1069 dB (from 100 samples)
Signa / Range	4.12527 dB / 123.027 dB
Cp / Cpk	1.61 / 0.47
Samples	100



Summary

- The impedance compensated cantilever probe (U+) has been successful developed and validated the superior RF performance of the probe card. (Patent pending)



Application & Specification

- **S11_{-10dB} Bandwidth: > 6GHz**
- **Fine pitch: < 35 um**
- **RF Application of U+ →
DTV, GPS, Mobile Phone, WIFI.**



Follow-On Work

- **Ongoing work ~ higher frequency device testing probe card for differential RF application devices.**



Acknowledgements

- **Great thanks to Innofidei :
Jamie, John.**
- **MPI Probe Card Center Engineering Team**



Q & A

Thank you very much .

